



PIC12F629/675

8-Pin ELASH-Based 8-Bit CMOS Microcontroller

High Performance RISC CPU:

- Only 35 instructions to learn
 - All single cycle instructions except branches
- Operating speed:
 - DC - 20 MHz oscillator/clock input
 - DC - 200 ns instruction cycle
- Interrupt capability
- 8-level deep hardware stack
- Direct, Indirect, and Relative Addressing modes

Special Microcontroller Features:

- Internal and external oscillator options
 - Precision Internal 4 MHz oscillator factory calibrated to $\pm 1\%$
 - External Oscillator support for crystals and resonators
 - 5 μ s wake-up from SLEEP, 3.0V, typical
- Power saving SLEEP mode
- Wide operating voltage range - 2.0V to 5.5V
- Industrial and Extended temperature range
- Low power Power-on Reset (POR)
- Power-up Timer (PWRT) and Oscillator Start-up Timer (OST)
- Brown-out Detect (BOD)
- Watchdog Timer (WDT) with independent oscillator for reliable operation
- Multiplexed $\overline{\text{MCLR}}$ /Input-pin
- Interrupt-on-pin change
- Individual programmable weak pull-ups
- Programmable code protection
- High Endurance FLASH/EEPROM Cell
 - 100,000 write FLASH endurance
 - 1,000,000 write EEPROM endurance
 - FLASH/Data EEPROM Retention: > 40 years

Low Power Features:

- Standby Current:
 - 1 nA @ 2.0V, typical
- Operating Current:
 - 8.5 μ A @ 32 kHz, 2.0V, typical
 - 100 μ A @ 1 MHz, 2.0V, typical
- Watchdog Timer Current
 - 300 nA @ 2.0V, typical
- Timer1 oscillator current:
 - 4 μ A @ 32 kHz, 2.0V, typical

Peripheral Features:

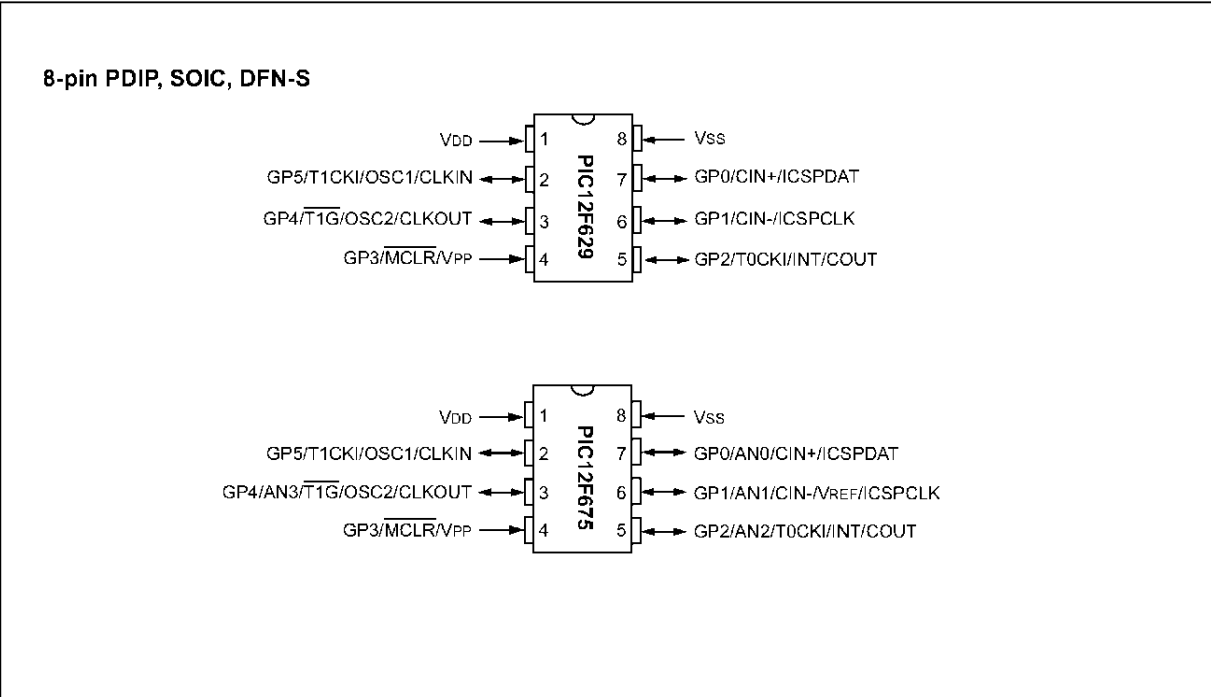
- 6 I/O pins with individual direction control
- High current sink/source for direct LED drive
- Analog comparator module with:
 - One analog comparator
 - Programmable on-chip comparator voltage reference (CVREF) module
 - Programmable input multiplexing from device inputs
 - Comparator output is externally accessible
- Analog-to-Digital Converter module (PIC12F675):
 - 10-bit resolution
 - Programmable 4-channel input
 - Voltage reference input
- Timer0: 8-bit timer/counter with 8-bit programmable prescaler
- Enhanced Timer1:
 - 16-bit timer/counter with prescaler
 - External Gate Input mode
 - Option to use OSC1 and OSC2 in LP mode as Timer1 oscillator, if INTOSC mode selected
- In-Circuit Serial Programming™ (ICSP™) via two pins

Device	Program Memory	Data Memory		I/O	10-bit A/D (ch)	Comparators	Timers 8/16-bit
	FLASH (words)	SRAM (bytes)	EEPROM (bytes)				
PIC12F629	1024	64	128	6	–	1	1/1
PIC12F675	1024	64	128	6	4	1	1/1

* 8-bit, 8-pin devices protected by Microchip's Low Pin Count Patent: U.S. Patent No. 5,847,450. Additional U.S. and foreign patents and applications may be issued or pending.

PIC12F629/675

Pin Diagrams




14.0 PACKAGING INFORMATION

14.1 Package Marking Information


8-Lead PDIP (Skinny DIP)

XXXXXXXXX
XXXXXXXXN
○  YYWW


Example

12F629-I
/017
○  0215

8-Lead SOIC

XXXXXXXXX
XXXXYYWW
○  NNN


Example

12F629-E
/0215
○  017

8-Lead DFN-S

XXXXXXXXX
XXXXXXXXX
XXYYWW
○  NNN

Example

12F629
-E/021
0215
○  017

Legend:	XX...X	Customer specific information*
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code

Note:	In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line thus limiting the number of available characters for customer specific information.
--------------	--

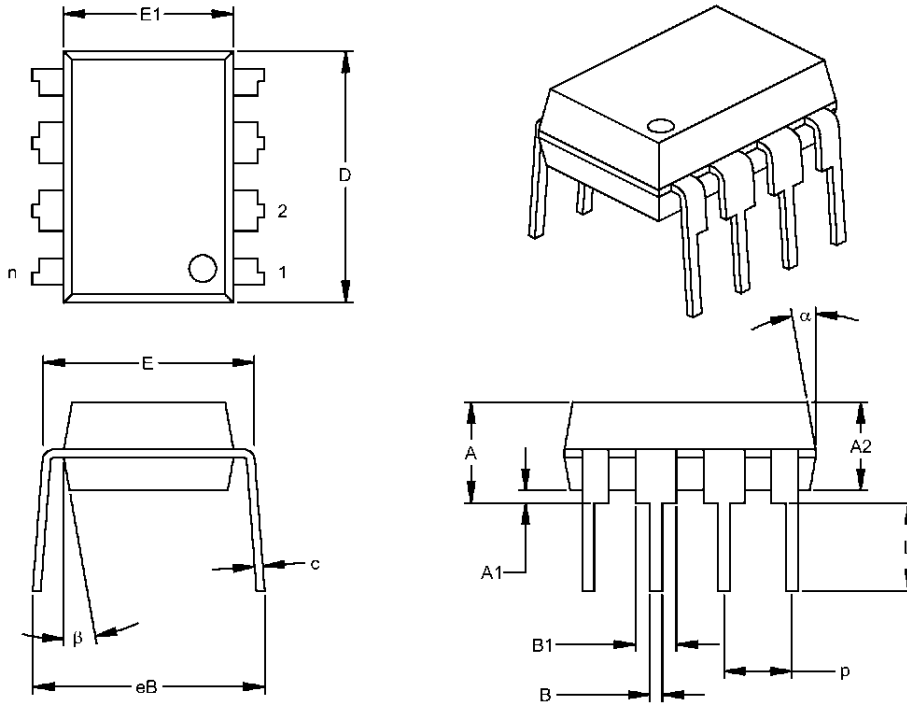
- * Standard PICmicro device marking consists of Microchip part number, year code, week code, and traceability code. For PICmicro device marking beyond this, certain price adders apply. Please check with your Microchip Sales Office. For QTP devices, any special marking adders are included in QTP price.

PIC12F629/675

14.2 Package Details

The following sections give the technical details of the packages.

8-Lead Plastic Dual In-line (P) – 300 mil (PDIP)



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.360	.373	.385	9.14	9.46	9.78
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	c	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	B	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	§ eB	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter

§ Significant Characteristic

Notes:

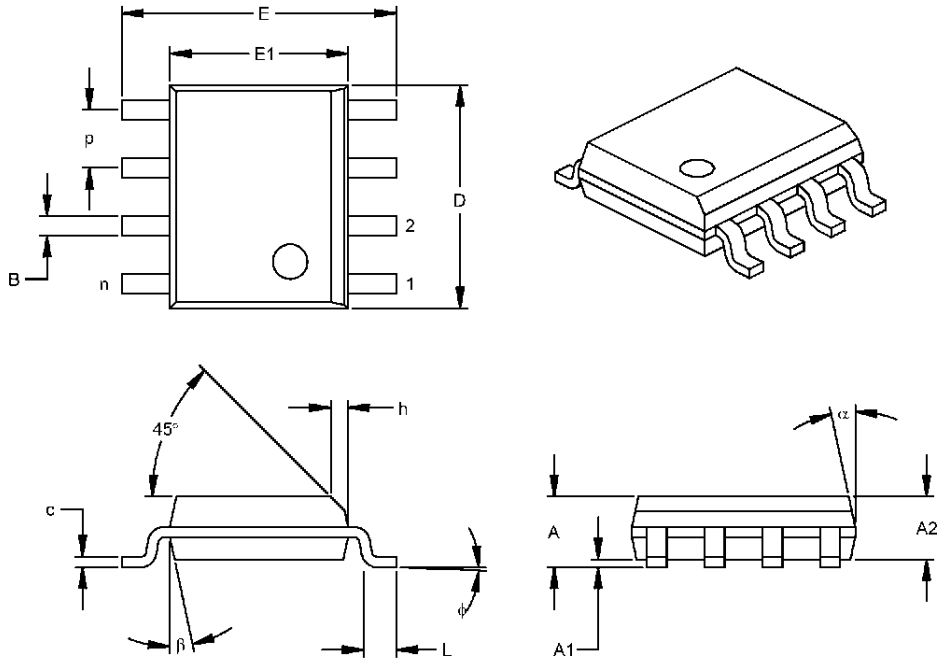
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-001

Drawing No. C04-018

PIC12F629/675

8-Lead Plastic Small Outline (SN) – Narrow, 150 mil (SOIC)



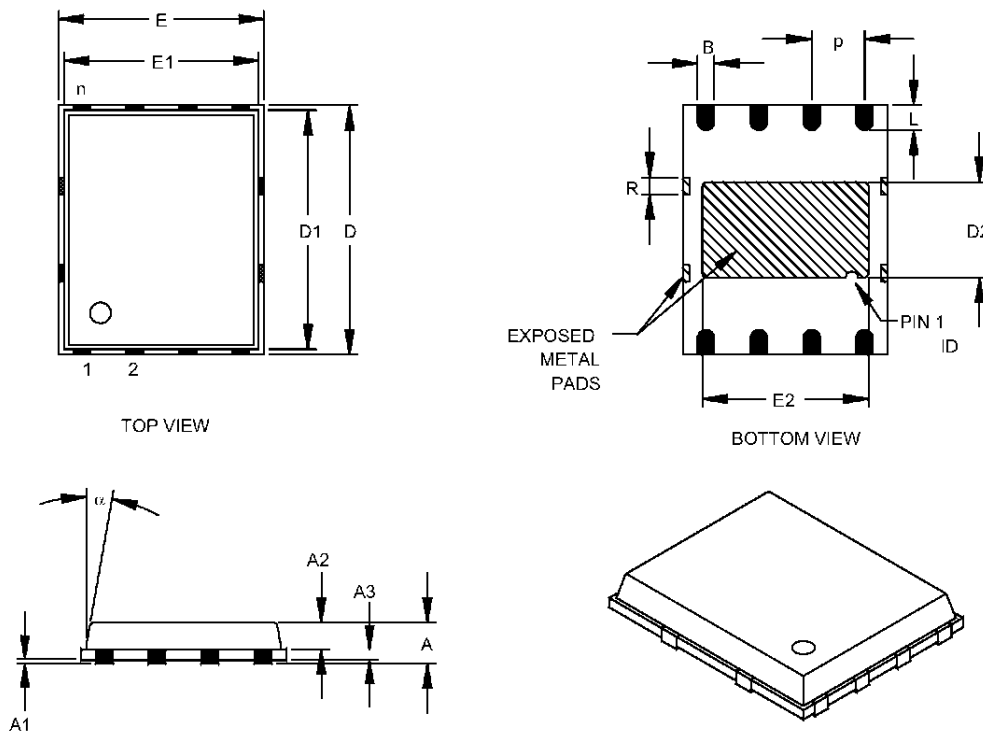
Units		INCHES*			MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	P		.050			1.27	
Overall Height	A	.053	.061	.069	1.35	1.55	1.75
Molded Package Thickness	A2	.052	.056	.061	1.32	1.42	1.55
Standoff §	A1	.004	.007	.010	0.10	0.18	0.25
Overall Width	E	.228	.237	.244	5.79	6.02	6.20
Molded Package Width	E1	.146	.154	.157	3.71	3.91	3.99
Overall Length	D	.189	.193	.197	4.80	4.90	5.00
Chamfer Distance	h	.010	.015	.020	0.25	0.38	0.51
Foot Length	L	.019	.025	.030	0.48	0.62	0.76
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.008	.009	.010	0.20	0.23	0.25
Lead Width	B	.013	.017	.020	0.33	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
 § Significant Characteristic

Notes:
 Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.
 JEDEC Equivalent: MS-012
 Drawing No. C04-057

PIC12F629/675

8-Lead Plastic Dual Flat No Lead Package (MF) 6x5 mm Body (DFN-S)



Dimension Limits	Units	INCHES			MILLIMETERS*		
		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		8			8	
Pitch	P	.050 BSC			1.27 BSC		
Overall Height	A		.033	.039		0.85	1.00
Molded Package Thickness	A2		.026	.031		0.65	0.80
Standoff	A1	.000	.0004	.002	0.00	0.01	0.05
Base Thickness	A3	.008 REF.			0.20 REF.		
Overall Length	E	.194 BSC			4.92 BSC		
Molded Package Length	E1	.184 BSC			4.67 BSC		
Exposed Pad Length	E2	.152	.158	.163	3.85	4.00	4.15
Overall Width	D	.236 BSC			5.99 BSC		
Molded Package Width	D1	.226 BSC			5.74 BSC		
Exposed Pad Width	D2	.085	.091	.097	2.16	2.31	2.46
Lead Width	B	.014	.016	.019	0.35	0.40	0.47
Lead Length	L	.020	.024	.030	0.50	0.60	0.75
Tie Bar Width	R		.014			.356	
Mold Draft Angle Top	α			12°			12°

*Controlling Parameter

Notes:

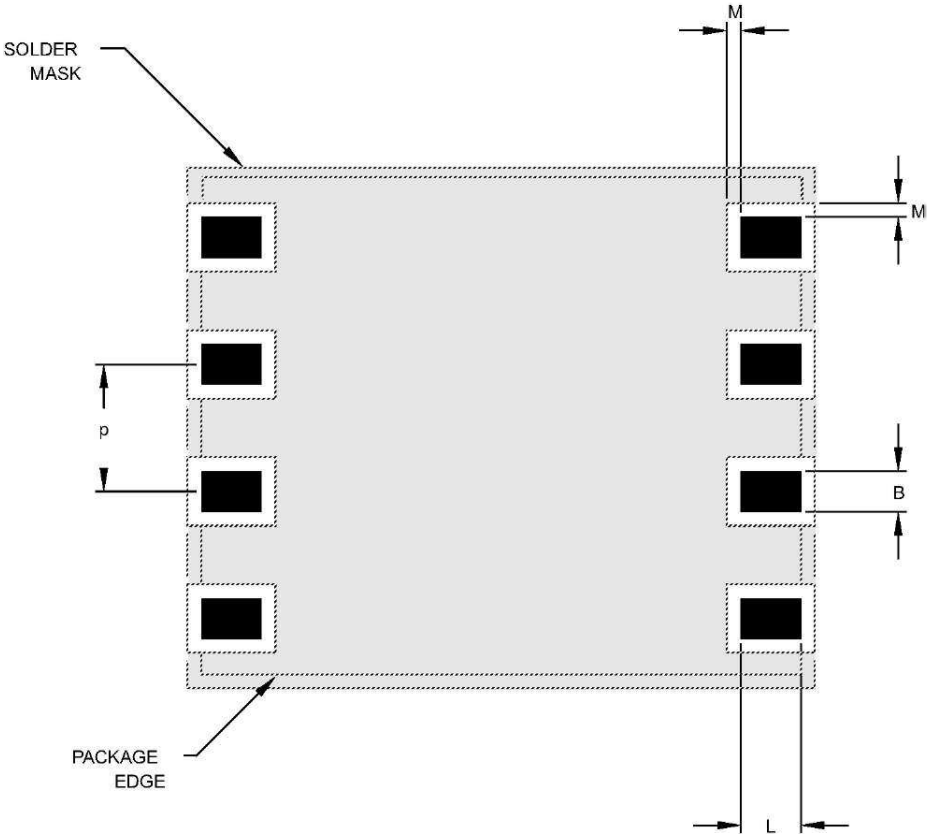
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC equivalent: pending

Drawing No. C04-113

PIC12F629/675

8-Lead Plastic Dual Flat No Lead Package (MF) 6x5 mm Body (DFN-S) Land Pattern and Solder Mask



Dimension Limits	Units	INCHES			MILLIMETERS*		
		MIN	NOM	MAX	MIN	NOM	MAX
Pitch	P	.050 BSC			1.27 BSC		
Pad Width	B	.014	.016	.019	0.35	0.40	0.47
Pad Length	L	.020	.024	.030	0.50	0.60	0.75
Pad to Solder Mask	M	.005		.006	0.13		0.15

*Controlling Parameter

Drawing No. C04-2113

PIC12F629/675

APPENDIX A: DATA SHEET REVISION HISTORY

Revision A

This is a new data sheet.

Revision B

Added characterization graphs.

Updated specifications.

Added notes to indicate Microchip programmers maintain all calibration bits to factory settings and the PIC12F675 ANSEL register must be initialized to configure pins as digital I/O.

Updated MLF-S package name to DFN-S.

APPENDIX B: DEVICE DIFFERENCES

The differences between the PIC12F629/675 devices listed in this data sheet are shown in Table B-1.

TABLE B-1: DEVICE DIFFERENCES

Feature	PIC12F629	PIC12F675
A/D	No	Yes

PIC12F629/675

APPENDIX C: DEVICE MIGRATIONS

This section is intended to describe the functional and electrical specification differences when migrating between functionally similar devices (such as from a PIC16C74A to a PIC16C74B).

Not Applicable

APPENDIX D: MIGRATING FROM OTHER PICmicro® DEVICES

This discusses some of the issues in migrating from other PICmicro devices to the PIC12F6XX family of devices.

D.1 PIC12C67X to PIC12F6XX

TABLE 1: FEATURE COMPARISON

Feature	PIC12C67X	PIC12F6XX
Max Operating Speed	10 MHz	20 MHz
Max Program Memory	2048 bytes	1024 bytes
A/D Resolution	8-bit	10-bit
Data EEPROM	16 bytes	64 bytes
Oscillator Modes	5	8
Brown-out Detect	N	Y
Internal Pull-ups	GP0/1/3	GP0/1/2/4/5
Interrupt-on-change	GP0/1/3	GP0/1/2/3/4/5
Comparator	N	Y

Note: This device has been designed to perform to the parameters of its data sheet. It has been tested to an electrical specification designed to determine its conformance with these parameters. Due to process differences in the manufacture of this device, this device may have different performance characteristics than its earlier version. These differences may cause this device to perform differently in your application than the earlier version of this device.

PIC12F629/675

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>X</u>	<u>/XX</u>	<u>XXX</u>
Device	Temperature Range	Package	Pattern
Device	PIC12F6XX: Standard V _{DD} range PIC12F6XXT: (Tape and Reel)		
Temperature Range	I = -40°C to +85°C E = -40°C to +125°C		
Package	P = PDIP SN = SOIC (Gull wing, 150 mil body) MF = MLF-S		
Pattern	3-Digit Pattern Code for QTP (blank otherwise)		

Examples:

- a) PIC12F629 - E/P 301 = Extended Temp., PDIP package, 20 MHz, QTP pattern #301
- b) PIC12F675 - I/SO = Industrial Temp., SOIC package, 20 MHz

* JW Devices are UV erasable and can be programmed to any device configuration. JW Devices meet the electrical requirement of each oscillator type.

Sales and Support

Data Sheets

Products supported by a preliminary Data Sheet may have an errata sheet describing minor operational differences and recommended workarounds. To determine if an errata sheet exists for a particular device, please contact one of the following:

1. Your local Microchip sales office
2. The Microchip Corporate Literature Center U.S. FAX: (480) 792-7277
3. The Microchip Worldwide Site (www.microchip.com)

Please specify which device, revision of silicon and Data Sheet (include Literature #) you are using.

New Customer Notification System

Register on our web site (www.microchip.com/cn) to receive the most current information on our products.